CRST040N10N, CRSS037N10N

SkyMOS1 N-MOSFET 100V, 3.3mΩ, 120A

Features

- Uses CRM(CQ) advanced SkyMOS1 technology
- Extremely low on-resistance $R_{DS(on)}$
- Excellent Q_gx$R_{DS(on)}$ product(FOM)
- Qualified according to JEDEC criteria

Applications

- Motor control and drive
- Battery management
- UPS (Uninterrupible Power Supplies)

Product Summary

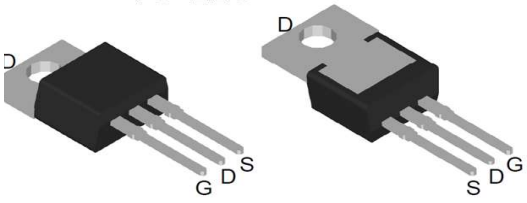
V_{DS}	100V
$R_{DS(on)}$	3.3mΩ
I_D	120A

100% DVDS Tested

100% Avalanche Tested

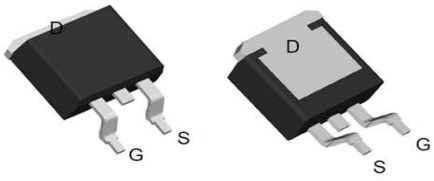
RoHS HF

TO-220

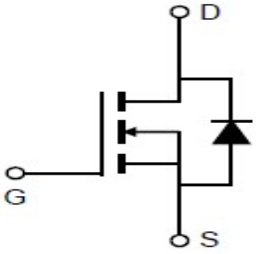


CRST040N10N

TO-263



CRSS037N10N



Package Marking and Ordering Information

Part #	Marking	Package	Packing	Reel Size	Tape Width	Qty
CRST040N10N	CRST040N10N	TO-220	Tube	N/A	N/A	50pcs
CRSS037N10N	CRSS037N10N	TO-263	Tape	N/A	N/A	1000pcs

Absolute Maximum Ratings

Parameter	**Symbol**	**Value**	**Unit**
Drain-source voltage	V_{DS}	100	V
Continuous drain current T_C = 25°C (Silicon limit) T_C = 25°C (Package limit) T_C = 100°C (Silicon limit)	I_D	 167 120 106	A
Pulsed drain current (T_C = 25°C, t_p limited by T_{jmax})	$I_{D\ pulse}$	480	A
Avalanche energy, single pulse (1D=34.5, Rg=25Ω)	E_{AS}	300	mJ
Gate-Source voltage	V_{GS}	±20	V
Power dissipation (T_C = 25°C)	P_{tot}	187	W
Operating junction and storage temperature	T_j , T_{stg}	-55...+150	°C
Soldering temperature, wave soldering only allowed at leads (1.6mm from case for 10s)	Tsold	260	°C

Thermal Resistance

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Thermal resistance, junction – case.	R_{thJC}	-	0.40	0.67	°C/W	
Thermal resistance, junction – ambient(min. footprint)	R_{thJA}	-	-	62	°C/W	

Electrical Characteristic (at Tj = 25 °C, unless otherwise specified)

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Static Characteristic						
Drain-source breakdown voltage	BV_{DSS}	100	-	-	V	V_{GS}=0V, I_D=250uA
Gate threshold voltage	$V_{GS(th)}$	2	3	4	V	V_{DS}=V_{GS},I_D=250uA
Zero gate voltage drain current	I_{DSS}	-	0.05	1	μA	V_{DS}=100V,V_{GS}=0V T_j=25°C
		-	-	100		T_j=125°C
Gate-source leakage current	I_{GSS}	-	±10	±100	nA	V_{GS}=±20V,V_{DS}=0V
Drain-source on-state resistance	$R_{DS(on)}$	-	3.3	4.0	mΩ	V_{GS}=10V, I_D=50A TO-220
		-	3	3.7		TO-263
Transconductance	g_{fs}	-	108	-	S	V_{DS}=5V,I_D=50A
Dynamic Characteristic						
Input Capacitance	C_{iss}	-	6920	10380	pF	V_{GS}=0V, V_{DS}=50V, f=1MHz
Output Capacitance	C_{oss}	-	1026	1539		
Reverse Transfer Capacitance	C_{rss}	-	33.4	66.8		
Gate Total Charge	Q_G	-	117	175.5	nC	V_{GS}=10V, V_{DS}=50V, I_D=50A, f=1MHz
Gate-Source charge	Q_{gs}	-	40	60		
Gate-Drain charge	Q_{gd}	-	37	74		
Turn-on delay time	$t_{d(on)}$	-	48	-	ns	V_{GS}=10V, V_{DS}=50V, R_G=3.0Ω
Rise time	t_r	-	56	-		
Turn-off delay time	$t_{d(off)}$	-	75	-		

Fall time	t_f	-	33	-		
Gate resistance	R_G	-	2.6	3.9	Ω	V_{GS}=0V, V_{DS}=0V, f=1MHz

Body Diode Characteristic

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Body Diode Forward Voltage	V_{SD}	-	0.85	1.3	V	V_{GS}=0V,I_{SD}=50A
Body Diode Continuous Forward Current	I_S	-	-	106	A	T_C = 25°C
Body Diode Pulsed Current	$I_{S\ pulse}$	-	-	422.2	A	T_C = 25°C
Body Diode Reverse Recovery Time	t_{rr}	-	60	120	ns	I_F=20A, dI/dt=500A/μs
Body Diode Reverse Recovery Charge	Q_{rr}	-	560	1120	nC	I_F=20A, dI/dt=500A/μs

Typical Performance Characteristics

Fig 1: Output Characteristics

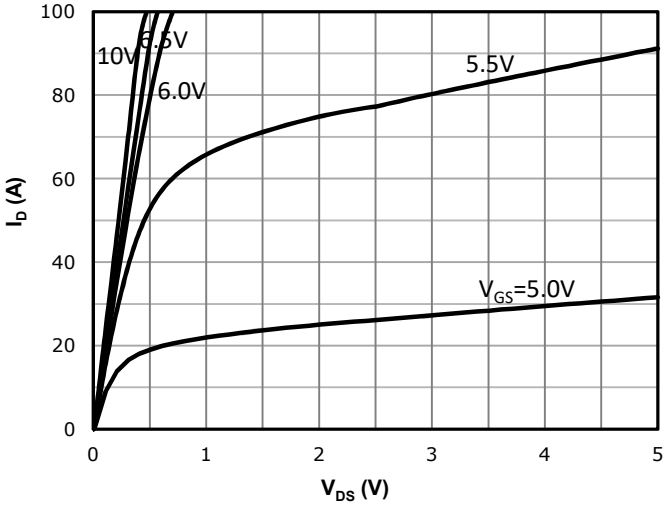


Fig 2: Transfer Characteristics

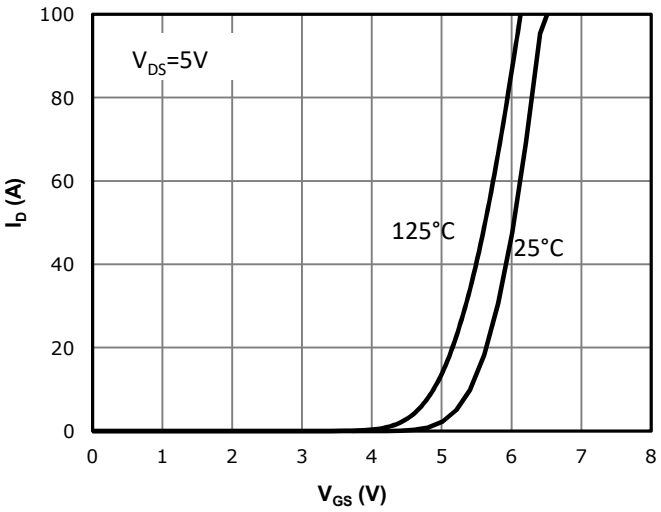


Fig 3: Rds(on) vs Drain Current and Gate Voltage

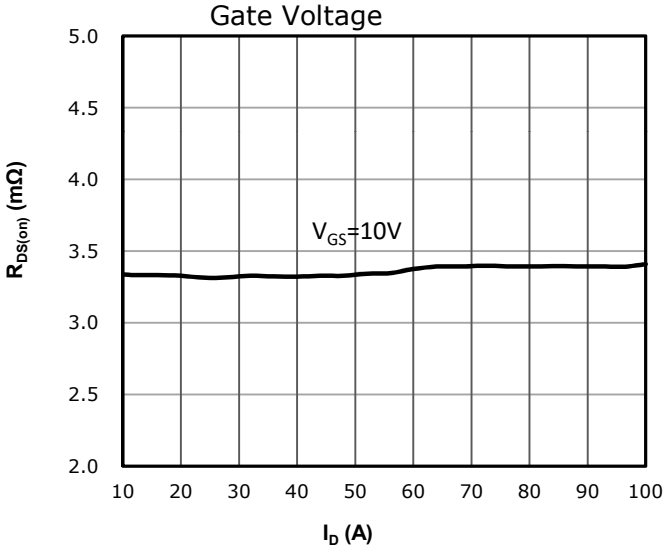


Fig 4: Rds(on) vs Gate Voltage

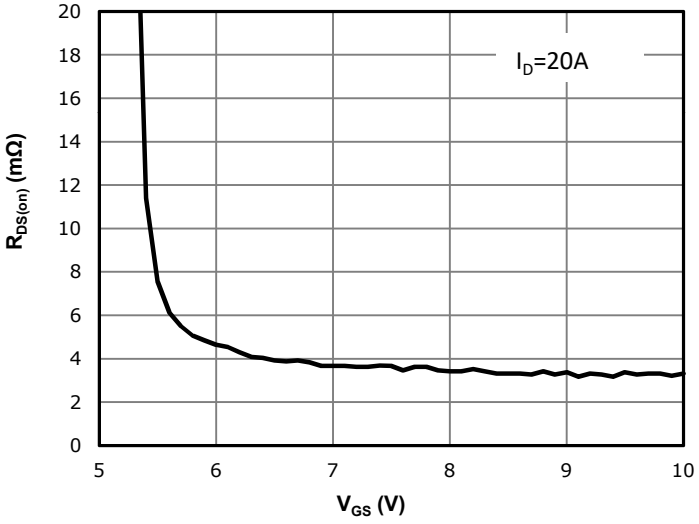


Fig 5: Rds(on) vs. Temperature

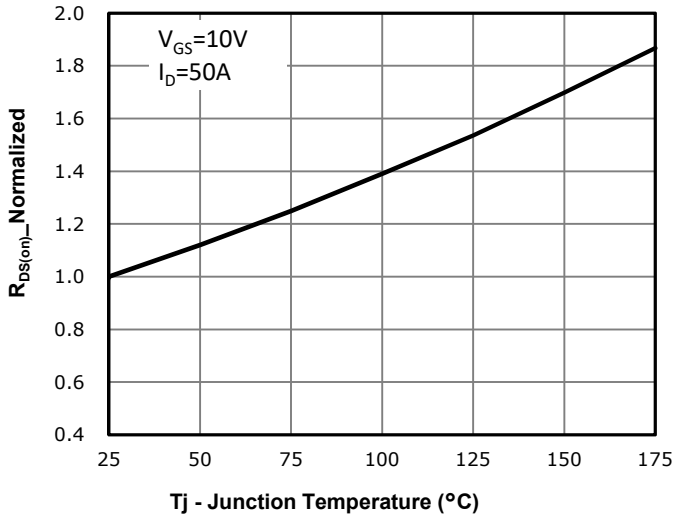


Fig 6: Capacitance Characteristics

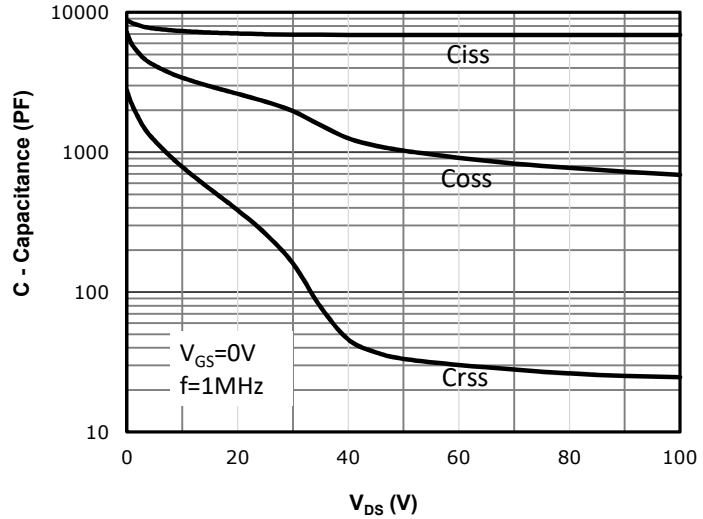


Fig 7: Gate Charge Characteristics

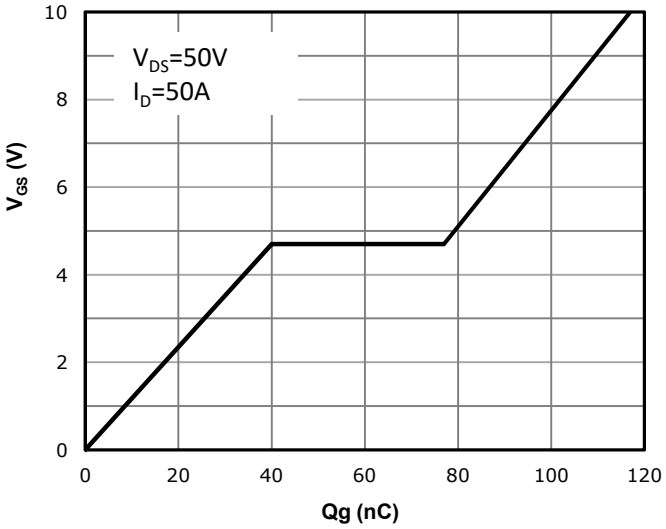


Fig 8: Body-diode Forward Characteristics

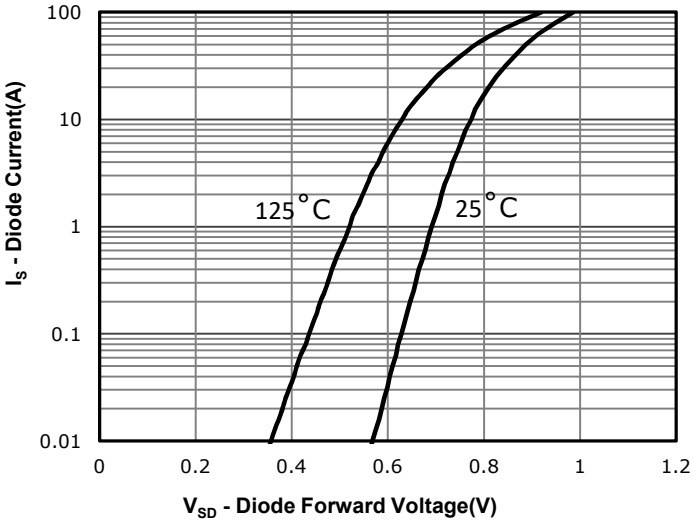


Fig 9: Power Dissipation

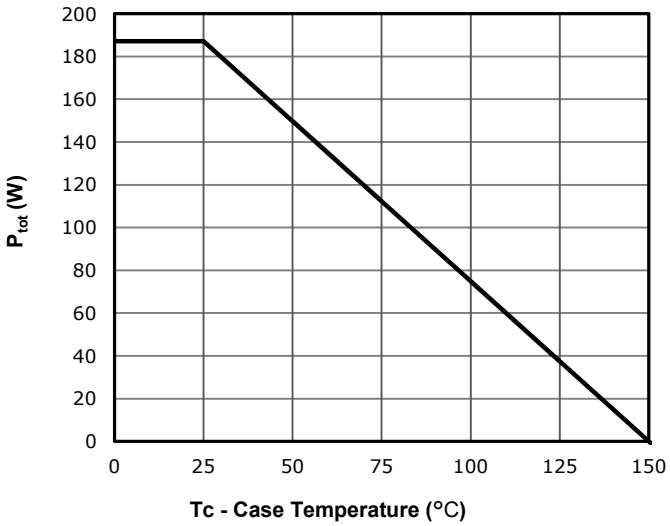


Fig 10: Drain Current Derating

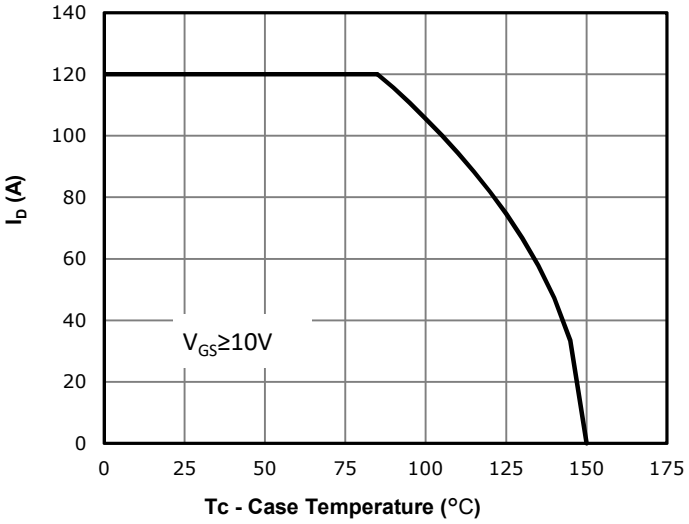


Fig 11: Safe Operating Area

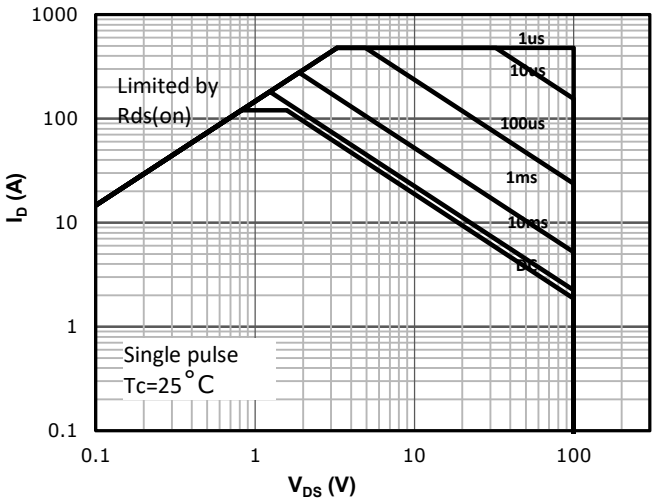
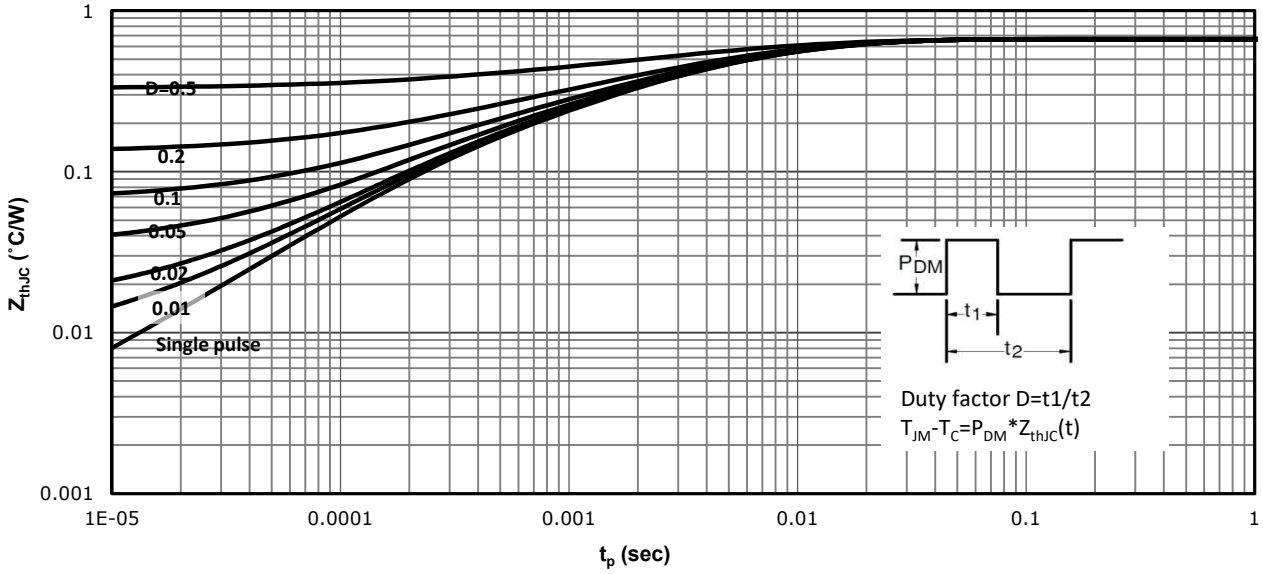
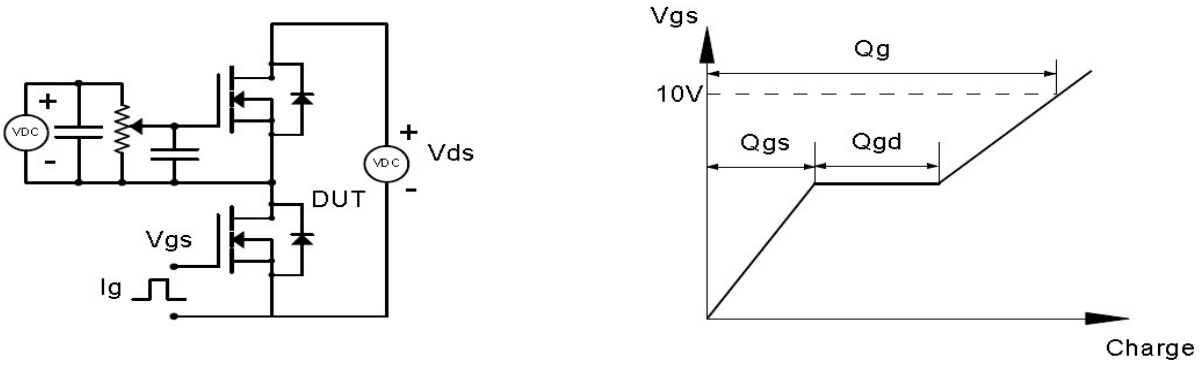


Fig 12: Max. Transient Thermal Impedance

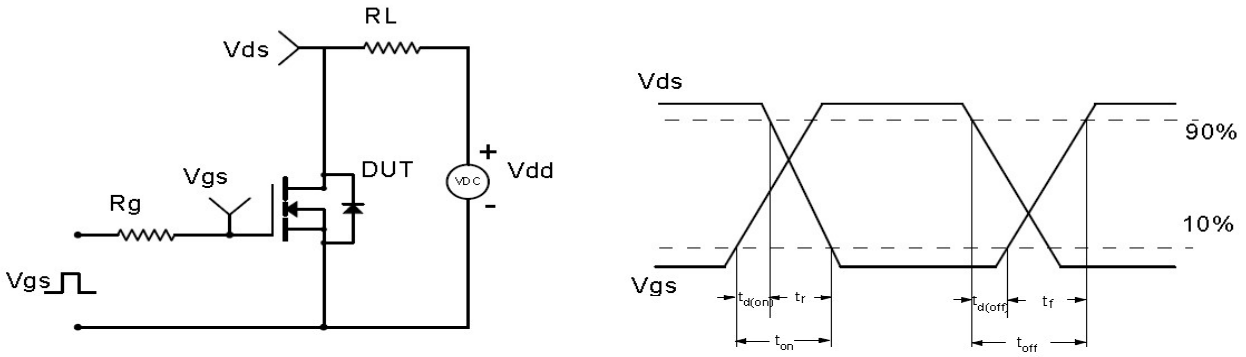


Test Circuit & Waveform

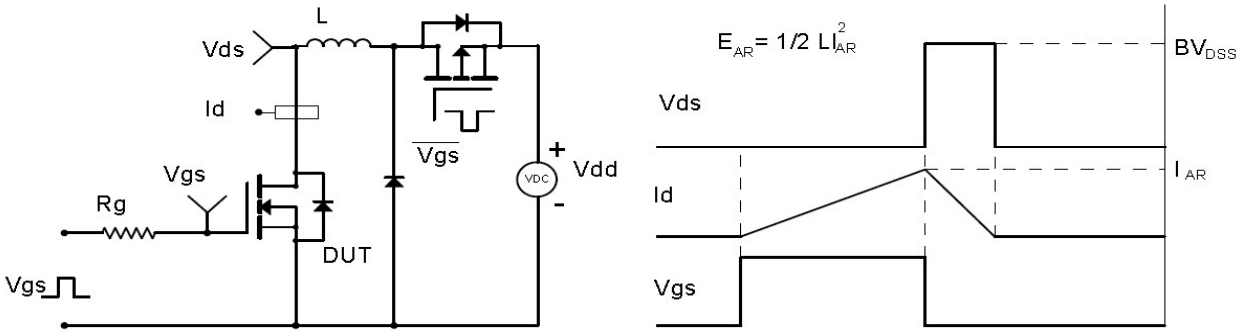
Gate Charge Test Circuit & Waveform



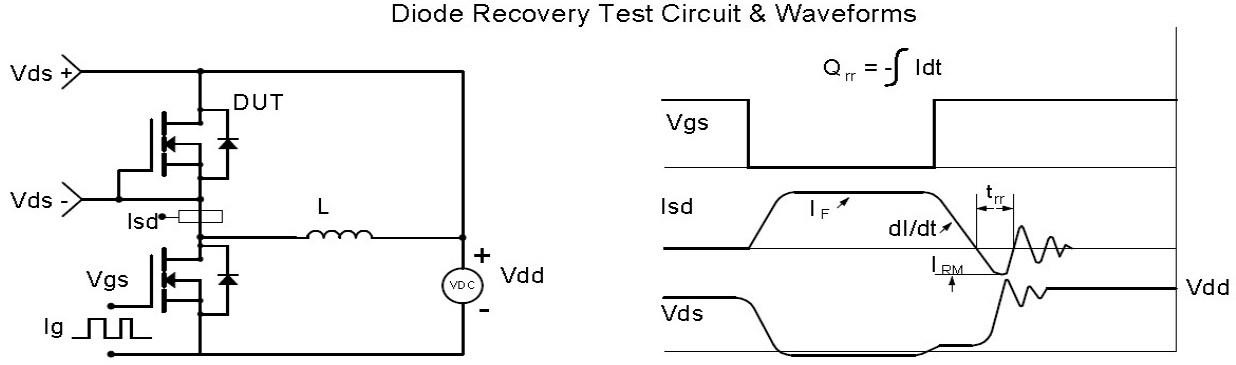
Resistive Switching Test Circuit & Waveforms



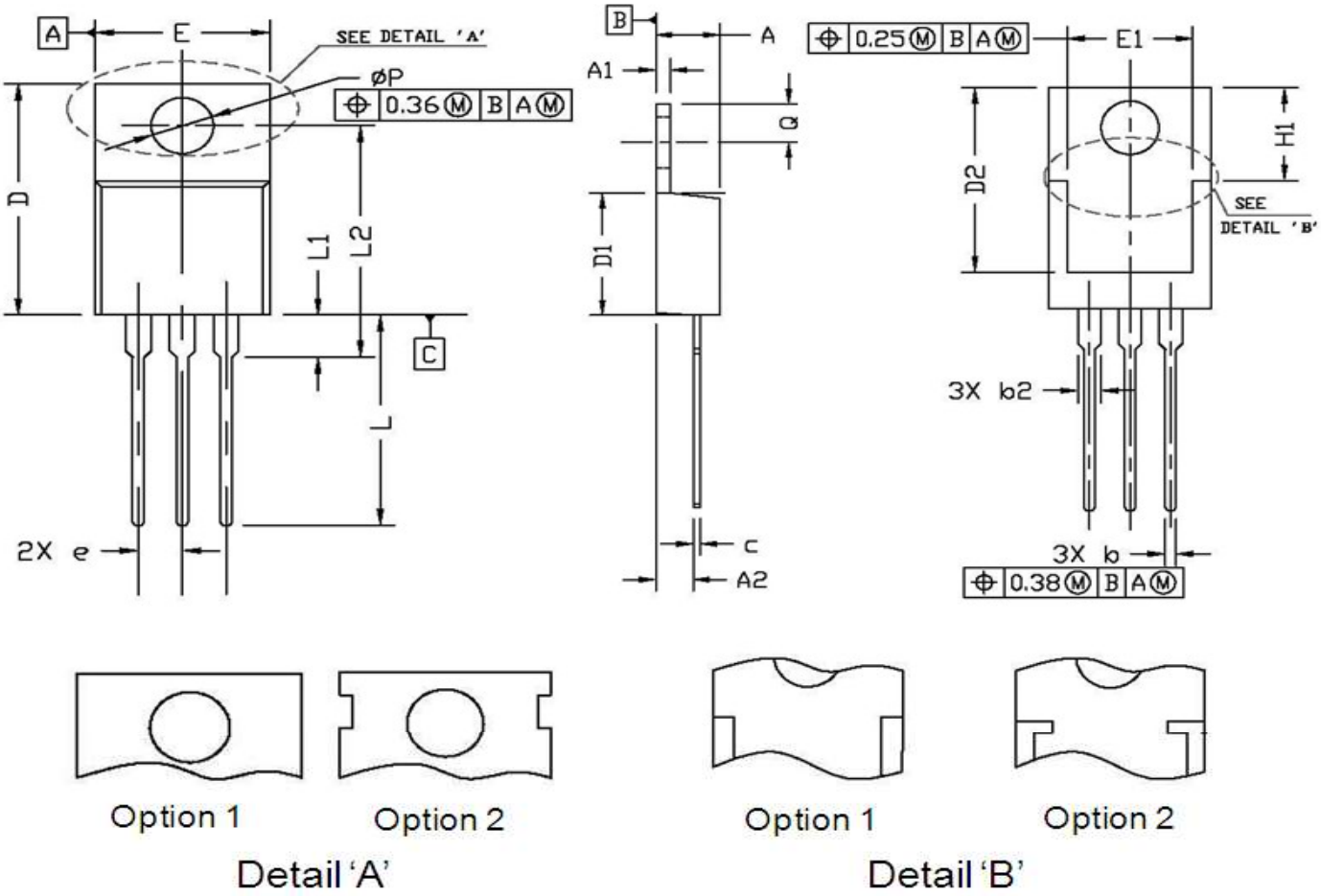
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

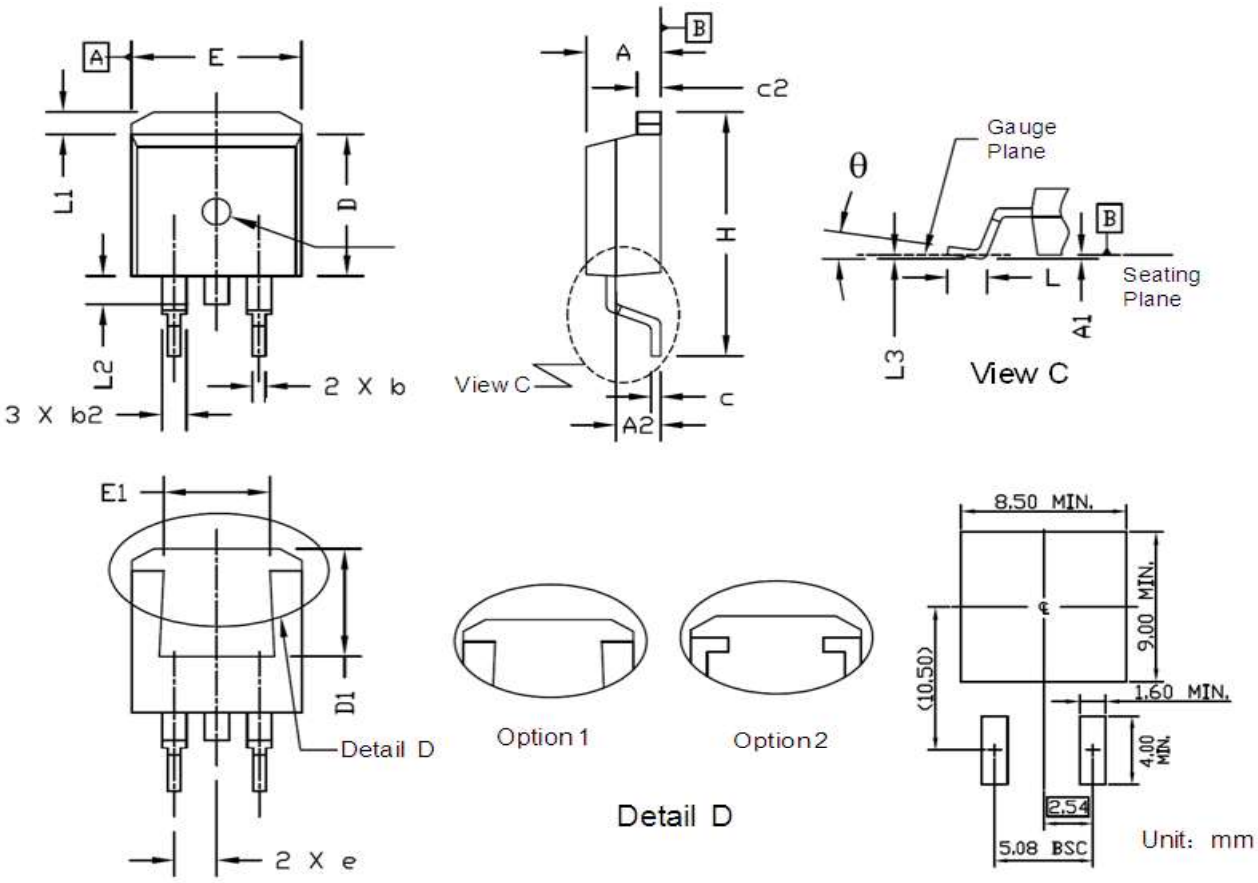


Package Outline: TO-220-3L



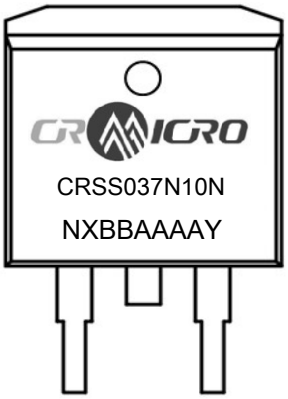
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.30	4.80	0.169	0.189
A1	1.20	1.45	0.047	0.057
A2	2.20	2.90	0.087	0.114
b	0.69	0.95	0.027	0.037
b2	1.00	1.60	0.039	0.063
c	0.33	0.65	0.013	0.026
D	14.70	16.20	0.579	0.638
D1	8.59	9.65	0.338	0.380
D2	11.75	13.60	0.463	0.535
e	2.54 BSC.		0.100 BSC.	
E	9.60	10.60	0.378	0.417
E1	7.00	8.89	0.276	0.350
H1	6.20	7.00	0.244	0.276
L	12.60	14.80	0.496	0.583
L1	2.70	3.80	0.106	0.150
L2	12.13	16.50	0.478	0.650
Q	2.40	3.10	0.094	0.122
P	3.50	3.95	0.138	0.156

Package Outline: TO-263



Symbol		Dimensions In Millimeters		Dimensions In Inches	
		Min.	Max.	Min.	Max.
A		4.30	4.86	0.169	0.191
A1		0.00	0.25	0.000	0.010
A2		2.20	2.90	0.087	0.114
b		0.68	0.94	0.027	0.037
b2		1.14	1.78	0.045	0.070
c		0.33	0.65	0.013	0.026
c2		1.17	1.40	0.046	0.055
D		8.38	9.45	0.330	0.372
D1		6.90	8.17	0.272	0.322
e		2.54 BSC.		0.100 BSC.	
E		9.78	10.50	0.385	0.413
E1		6.50	8.60	0.256	0.339
H		14.61	15.88	0.575	0.625
L		1.78	2.79	0.070	0.110
L1		0.70	1.60	0.028	0.063
L2		1.00	1.78	0.039	0.070
L3		0.25 BSC.		0.010 BSC.	
θ	Option A	-8°	0°	-8°	0°
	Option B	0°	8°	0°	8°

Marking



NOTE:
NXBBAAAAY

N	—Wire Bond code
X	—Assembly location code
BB	—Fab code
AAAA	—Lot code
Y	—Bin code

Revision History

Revison	Date	Major changes
1.0	2018/2/9	Release of formal version.
2.0	2019/5/28	Supplement Package outline info.
3.0	2019/12/15	Add identification&key parameter&package info update.

Disclaimer

Unless otherwise specified in the datasheet, the product is designed and qulified as a standard commercial product and is not intended for use in applications that require extraordinary levels of quality and reliability, such as automotive, aviation/aerospace and life-support devices or systems.

Any and all semicondutor products have certain probability to fail or malfunction, which may result in personal injury, death or property damage. Customer are solely responsible for providing adequate safe measures when design their systems.

CRM(CQ) reserves the right to improve product design, function and reliability without notice.